

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chang Kun PARK</td> <td>07/26/2013</td> </tr> <tr> <td>Ho Yong HWANG</td> <td>07/26/2013</td> </tr> </tbody> </table>		Name	Execution Date	Chang Kun PARK	07/26/2013	Ho Yong HWANG	07/26/2013				
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<table border="1"> <tr> <td>Name:</td> <td>SOONGSIL UNIVERSITY RESEARCH CONSORTIUM TECHNO-PARK</td> </tr> <tr> <td>Street Address:</td> <td>511, Sangdo-dong, Dongjak-gu</td> </tr> <tr> <td>City:</td> <td>Seoul</td> </tr> <tr> <td>State/Country:</td> <td>KOREA, REPUBLIC OF</td> </tr> <tr> <td>Postal Code:</td> <td>156-030</td> </tr> </table>		Name:	SOONGSIL UNIVERSITY RESEARCH CONSORTIUM TECHNO-PARK	Street Address:	511, Sangdo-dong, Dongjak-gu	City:	Seoul	State/Country:	KOREA, REPUBLIC OF	Postal Code:	156-030
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CORRESPONDENCE DATA											
Fax Number: 7039358473 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 571-313-7556 Email: mail@sherr-law.com Correspondent Name: SHERR & JIANG, PLLC Address Line 1: 620 HERNDON PARKWAY Address Line 2: SUITE 320 Address Line 4: HERNDON, VIRGINIA 20170											
ATTORNEY DOCKET NUMBER:	523-0087										
NAME OF SUBMITTER:	Daniel H. Sherr										
Signature:	/Daniel H. Sherr./										
Date:	08/07/2013										

This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 2

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**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN
APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE**

Title of
Invention

**POWER VOLTAGE SUPPLY APPARATUS FOR THREE DIMENSIONAL
SEMICONDUCTOR**

As the below named inventor, I hereby declare that:

This declaration
is directed to:



The attached application, or



United States application or PCT international application number _____
filed on _____.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

WHEREAS, SOONGSHI UNIVERSITY RESEARCH CONSORTIUM TECHNO-PARK, with offices at 311, Gangdo-dong, Dongjak-gu, Seoul 156-030 Republic of Korea (hereinafter referred to as ASSIGNEE), is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or renewals of any Letters patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

LEGAL NAME OF INVENTOR

Inventor: PARK, Chang Kun

Date: July 26, 2013

Signature: ChangKun Park

SHERR & JIANG, PLLC
620 HEENDON PARKWAY, SUITE 520
HERNDON, VA 20170
Tel: (703) 313-7556 | Fax: (703) 935-8473

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representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and
to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all
priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention
Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to
any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and
countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said
ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its
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LEGAL NAME OF INVENTOR

Inventor: HWANG, Ho Yong

Date: July 26, 2013

Signature: 

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TEL: (571) 313-7536 | FAX: (703) 935-8473

PATENT

RECORDED: 08/07/2013

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